2SD2140

Silicon NPN triple diffusion planar type

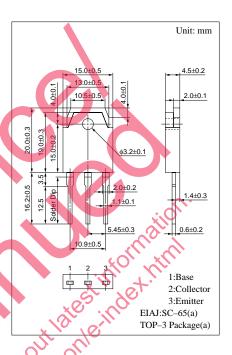
For high power amplification Complementary to 2SB1421

Features

- Satisfactory foward current transfer ratio h_{FE} vs. collector current I_C characteristics
- Wide area of safe operation (ASO)
- High transition frequency f_T
- Optimum for the output stage of a HiFi audio amplifier

Absolute Maximum Ratings (T_C=25°C)

Parameter	Sy	mbol	Ratings	_ \	Unit	
Collector to base volta	ige V	СВО	140		V	
Collector to emitter vol	tage V	CEO	140		V	
Emitter to base voltag	e V	EBO	5		V	
Peak collector current	I	CP CP	12		Α	
Collector current	I	. 4	7		A	
Collector power T _C =2			80		W	
dissipation Ta=2	5°C P	C	2.5		W	
Junction temperature	1	j	150		°C	
Storage temperature	T	stg	-55 to +15	0	°C	



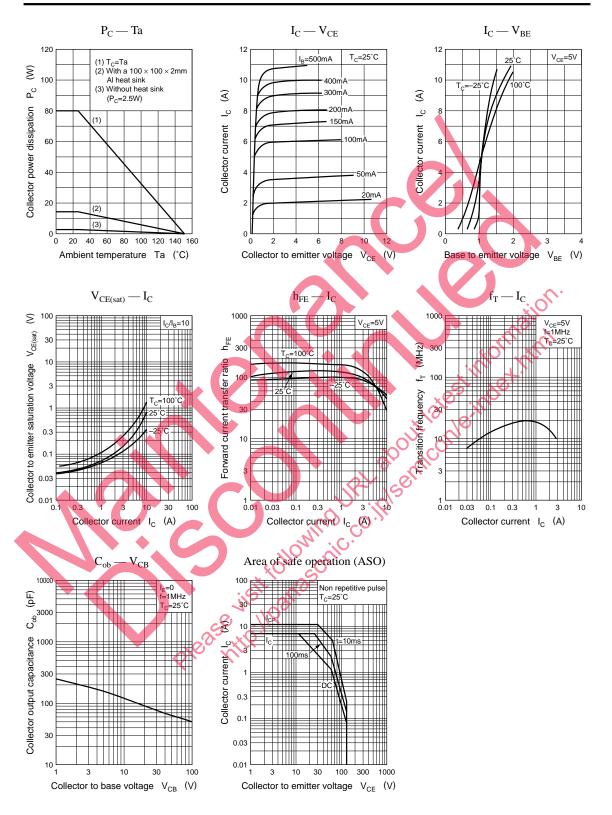
Electrical Characteristics (T_C=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = 140V, I_E = 0$			50	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = 3V \cdot I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE1}	$V_{CE} = 5V, I_{C} = 20mA$	20			
	h _{FE2} *	$V_{CE} = 5V, I_{C} = 1A$	60		200	
	h _{FE} 3	$V_{\rm CE} = 5$ V, $I_{\rm C} = 5$ A	20			
Base to emitter voltage	V_{BE}	$V_{CE} = 5V$, $I_C = 5A$			1.8	V
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 5A, I_B = 0.5A$			2.0	V
Transition frequency	f_T	$V_{CE} = 5V, I_{C} = 0.5A, f = 1MHz$		20		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10V, I_{E} = 0, f = 1MHz$		110		pF

*h_{FE2} Rank classification

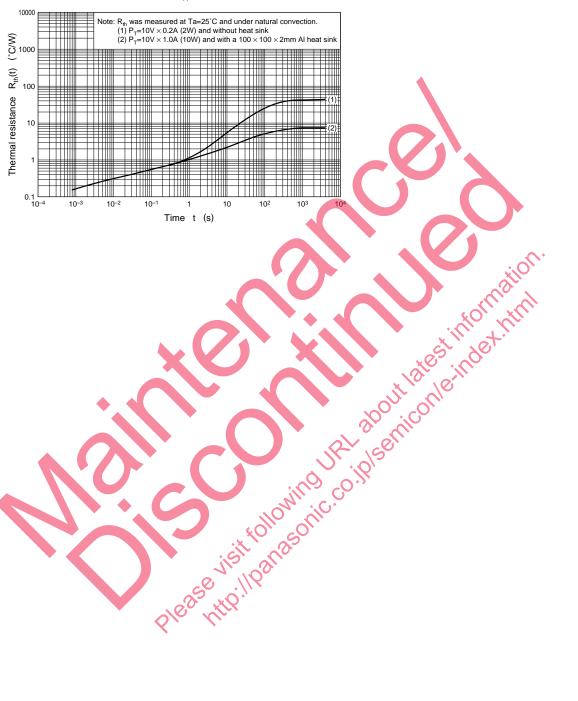
Rank	Q	S	P
h _{FE2}	60 to 120	80 to 160	100 to 200

Power Transistors 2SD2140



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